

Hong Kong Exchanges and Clearing Limited and The Stock Exchange of Hong Kong Limited take no responsibility for the contents of this announcement, make no representation as to its accuracy or completeness and expressly disclaim any liability whatsoever for any loss howsoever arising from or in reliance upon the whole or any part of the contents of this announcement.

This announcement is for information only and is not intended to and does not constitute, or form part of, an invitation or offer to acquire, purchase or subscribe for any securities of the Company.



HUA HONG SEMICONDUCTOR LIMITED

華虹半導體有限公司

(Incorporated in Hong Kong with limited liability)

(Stock Code: 1347)

INSIDE INFORMATION

DETERMINATION OF OFFER SIZE AND OFFER PRICE FOR PROPOSED RMB SHARE ISSUE UNDER SPECIFIC MANDATE AND PROGRESS OF SUBSCRIPTION BY A CONNECTED PERSON AS A STRATEGIC INVESTOR UNDER PROPOSED RMB SHARE ISSUE

This announcement is made by Hua Hong Semiconductor Limited (the “**Company**”) pursuant to Rule 13.09 of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited (the “**Hong Kong Listing Rules**”) and the Inside Information Provisions under Part XIVA of the Securities and Futures Ordinance (Chapter 571 of the Laws of Hong Kong).

Reference is made to the Company’s announcements dated 21 March 2022, 12 May 2022, 27 June 2022, 4 November 2022, 30 January 2023, 13 April 2023, 10 May 2023, 17 May 2023, 28 May 2023, 7 June 2023, 28 June 2023, 5 July 2023, 14 July 2023, 18 July 2023 and 21 July 2023 and the Company’s circulars dated 7 June 2022, 5 June 2023 and 29 June 2023 in relation to, among others, the RMB Share Issue. Unless otherwise defined, the capitalized terms used in this announcement shall have the same meanings as those defined in the above announcements and circulars.

I. DETERMINATION OF OFFER SIZE AND OFFER PRICE FOR RMB SHARE ISSUE UNDER SPECIFIC MANDATE

The Board is pleased to announce that, following the completion of preliminary price consultations among enquiry targets on 20 July 2023, the Company will issue 407,750,000 RMB Shares at the offer price of RMB52.00 per RMB Share, representing approximately 23.76% of the total share capital of the Company after the RMB Share Issue.

The offer price was negotiated and determined by the Company and the lead underwriters based on the result of the preliminary price consultations taking into account aspects including the reasonable investment value of the Company, valuation standards of comparable companies in secondary market, valuation standards of the relevant industry in secondary market, and duly considering factors including the effective subscription multiples of offline investors, market conditions, the need for proceeds and underwriting risks. There will no longer be any cumulative tender price consultation for the offline placement.

For the relevant terms of the proposed RMB Share Issue, please refer to the full text of the Issue Announcement of Hua Hong Semiconductor Limited for the Initial Public Offering and Listing of Shares on the STAR Market (《華虹半導體有限公司首次公開發行股票並在科創板上市發行公告》) published by the Company in Chinese only on the website of Shanghai Stock Exchange (www.sse.com.cn) and the website of the Hong Kong Exchanges and Clearing Limited (www.hkexnews.hk) and the website of the Company (<https://www.huahonggrace.com>) on 24 July 2023.

II. PROGRESS OF SUBSCRIPTION BY CONNECTED PERSON AS STRATEGIC INVESTOR UNDER THE RMB SHARE ISSUE

Reference is made to the announcement dated 28 June 2023 and the circular dated 29 June 2023 of the Company in relation to the proposed subscription by a connected person as a strategic investor under the proposed RMB Share Issue. As approved by the extraordinary general meeting of the Company on 14 July 2023, China IC Fund II will participate in the RMB Share Issue as a strategic investor by subscribing for RMB Shares under the RMB Share Issue up to an aggregate subscription amount of RMB3,000,000,000, subject to allotment.

The Board is pleased to announce that the Company has determined the final number of RMB Shares allotted to China IC Fund II under the China IC Fund II Subscription Agreement, being 48,334,249 RMB Shares with an aggregate allotted amount of RMB2,513,380,948.00.

The Company will make further disclosures on the developments of the RMB Share Issue as and when appropriate in accordance with the Hong Kong Listing Rules and other applicable laws and regulations.

This announcement is for information only and is not intended to and does not constitute, or form part of, an invitation or offer to acquire, purchase or subscribe for any securities of the Company.

By order of the Board
Hua Hong Semiconductor Limited
Mr. Suxin Zhang
Chairman and Executive Director

Shanghai, 24 July 2023

As at the date of this announcement, the directors of the Company are:

Executive Directors

Suxin Zhang (*Chairman*)

Junjun Tang (*President*)

Non-Executive Directors

Guodong Sun

Jing Wang

Jun Ye

Independent Non-Executive Directors

Stephen Tso Tung Chang

Kwai Huen Wong, JP

Long Fei Ye